

FOR IMMEDIATE RELEASE

Aismalibar North America to Showcase Advanced Thermal Management Materials at PCB West 2026

SANTA CLARA, Calif., September 28, 2026 – Aismalibar North America will showcase advanced thermal interface materials, thermally conductive PCB materials and insulated metal substrates at PCB West 2026 on Wednesday, September 30, at the Santa Clara Convention Center in Santa Clara, California. The company will meet with PCB designers, engineers and manufacturers to discuss materials that improve heat transfer and provide electrical insulation in demanding electronics and power applications.

As electronic systems increase in power density, effective heat transfer and electrical insulation are critical to performance, reliability and product life. Aismalibar develops materials engineered to move heat away from critical components while providing the dielectric performance required for high-voltage applications.

Advanced Thermal Interface Materials

Aismalibar will feature its latest generation of Thermal Interface Materials (TIMs), including BOND SHEET CURED GLASS FREE, developed to provide high thermal conductivity and reliable electrical insulation between heat-generating components and cooling surfaces.

The glass-free technology eliminates traditional glass reinforcement, allowing the dielectric formulation to deliver improved thermal performance and mechanical flexibility. Available in a range of dielectric thicknesses and insulation levels, these materials can be engineered around the thermal and electrical requirements of the application.

Glass Free Thermally Conductive PCB Materials

Aismalibar will also showcase its next-generation glass-free thermally conductive dielectric technology for single-sided and multilayer printed circuit boards. The material provides thermal conductivity up to 10 W/mK, with dielectric thickness options ranging from 50 to 200 microns and dielectric strength from approximately 3 to 10 kV, depending on the construction.

By combining thermal conductivity with electrical insulation, Aismalibar's glass-free bond sheet technology provides designers with an alternative to conventional glass-reinforced PCB materials in applications where efficient heat removal is critical.

Aismalibar will also feature its HTC 3.2 W/mK high-Tg bond sheets and thin laminates, developed to improve heat transfer through the PCB and reduce dependence on conventional thermal-via strategies. In appropriate applications, improved PCB-level thermal management can significantly reduce component operating temperatures, supporting increased output, reliability and product life.

High Performance Insulated Metal Substrates

For applications requiring even greater heat dissipation, Aismalibar will present its COBRITHERM insulated metal substrate (IMS) technologies, including COBRITHERM ULTRATHIN 5W and 8W materials.

Aismalibar's IMS constructions combine a metal base with a proprietary thermally conductive polymer-ceramic dielectric and copper circuitry, providing an efficient thermal path while maintaining electrical insulation. These materials are designed for demanding power electronics applications where high heat loads must be transferred rapidly away from power components. Compatibility with conventional PCB manufacturing and direct SMD assembly allows designers to incorporate advanced thermal management directly into the electronic substrate.

Meet Aismalibar at PCB West

Engineers, designers and manufacturers attending PCB West are invited to meet the Aismalibar North America team to discuss their thermal management challenges and explore material solutions for improved heat dissipation, electrical insulation and system reliability.

The PCB West exhibition takes place September 30 from 10 a.m. to 6 p.m. at the Santa Clara Convention Center. The technical conference runs September 29 through October 2. For more information, visit www.aismalibar.com and www.pcbwest.com.

About Aismalibar

Aismalibar develops and manufactures advanced thermal management materials for the electronics industry, including insulated metal substrates, thermally conductive laminates, bond sheets and thermal interface materials. Its technologies are used in automotive, power electronics, battery, LED, telecommunications, renewable energy and other demanding electronic applications where effective thermal management and electrical reliability are critical.

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